

專為車用存儲需求的高速低成本 串列式NAND方案

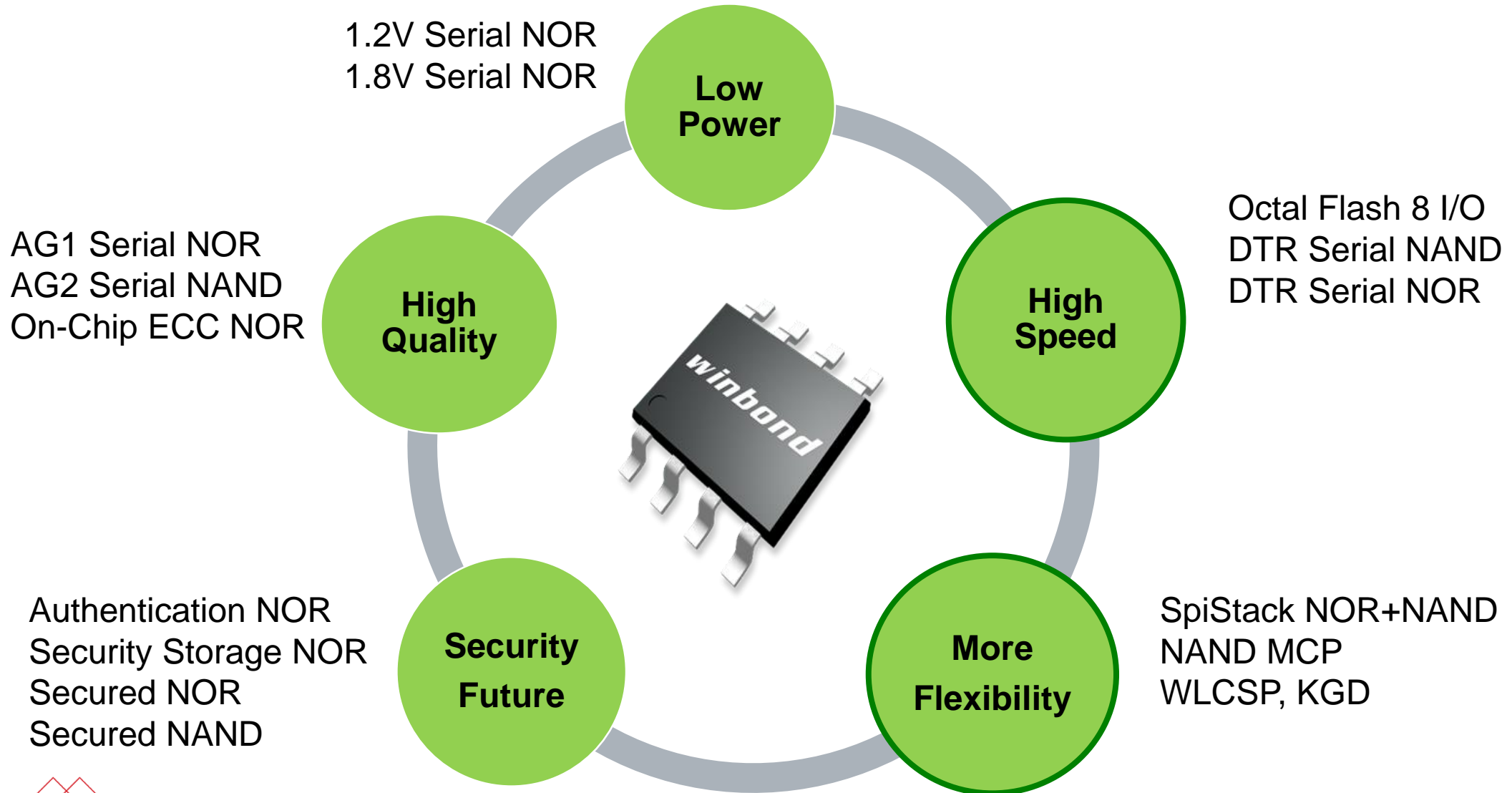
于緯良 Will Yu

快閃記憶體產品企劃技術副理

winbond
We Deliver

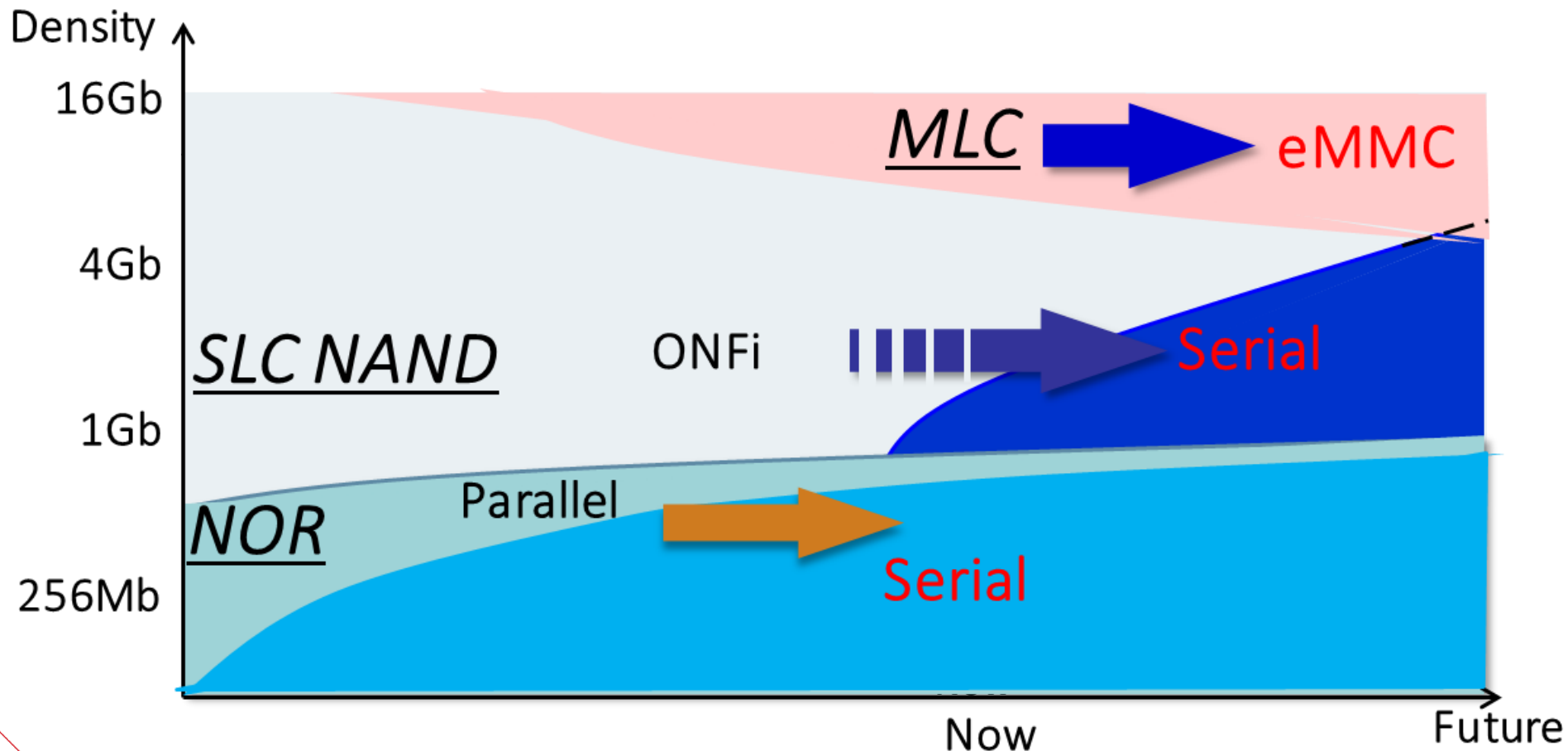
A Global Supplier of
Advanced Memory Solutions

- 01** 從**成本**考慮上，
串列式NAND 相比於串列式NOR，有何優勢？
- 02** 從**質量**角度上，
串列式NAND 與串列式NOR 的比較？
- 03** 從**讀取**速度上，
串列式NAND 與串列式NOR 的比較？
- 04** 從**寫入**速度上，
串列式NAND 與串列式NOR 的比較？
- 05** 串列式NAND 需要額外控制器做壞塊管理或 ECC 嗎？

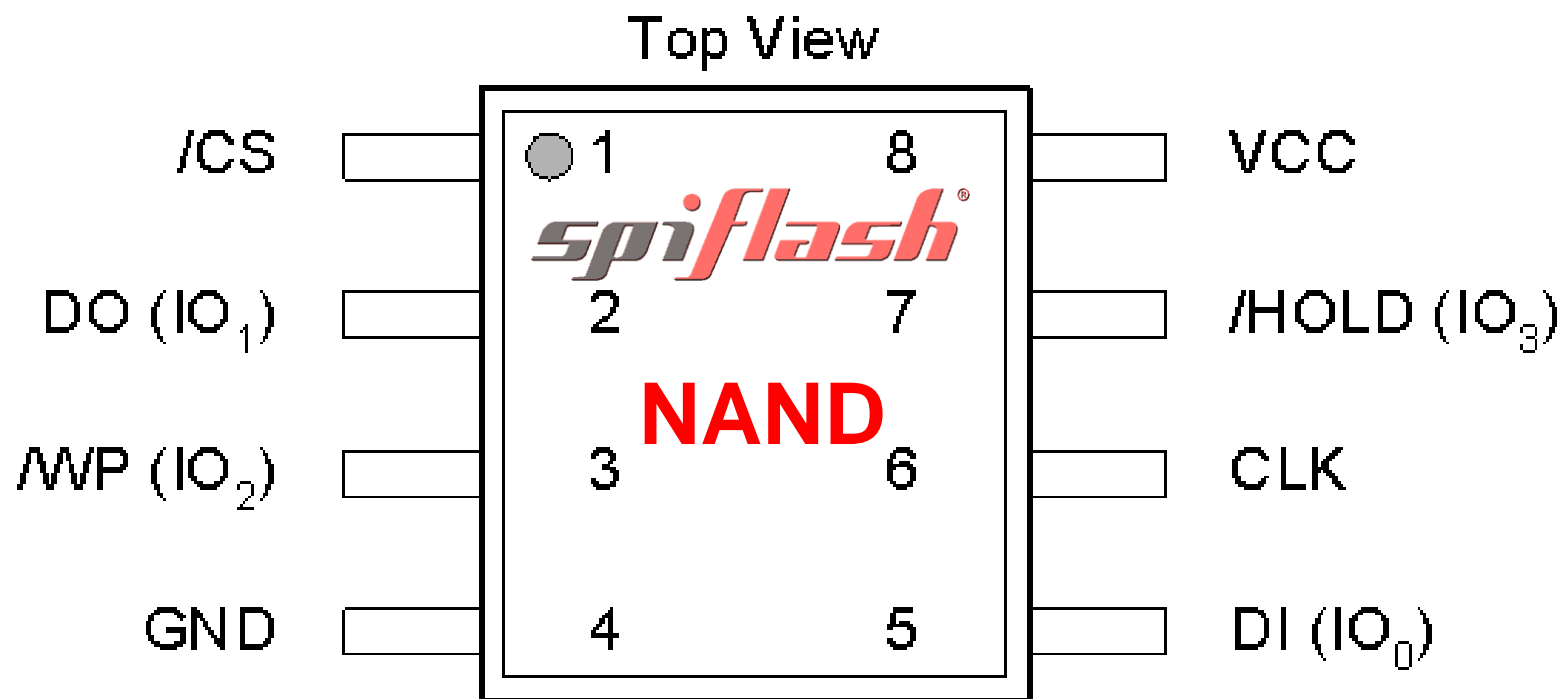


串列式NAND是趨勢

- ◇ 串列式NAND應用比例將超越SLC並口NAND。
- ◇ 部份高容量串列式NOR市場已經被串列式NAND取代。



- ◇ 硬體相容使導入串列式**NAND**的速度加快!
- ◇ 具有寫入速度快, 低成本, 相當品質的優點!



圖為華邦串列式NAND **W25N**系列

傳統 上

NOR

More Reliable

Low Density for Code

NAND

Not Perfect

Required “managed”

趨勢 上

NOR

High Density Demand Increased
Process Stop Shrinking

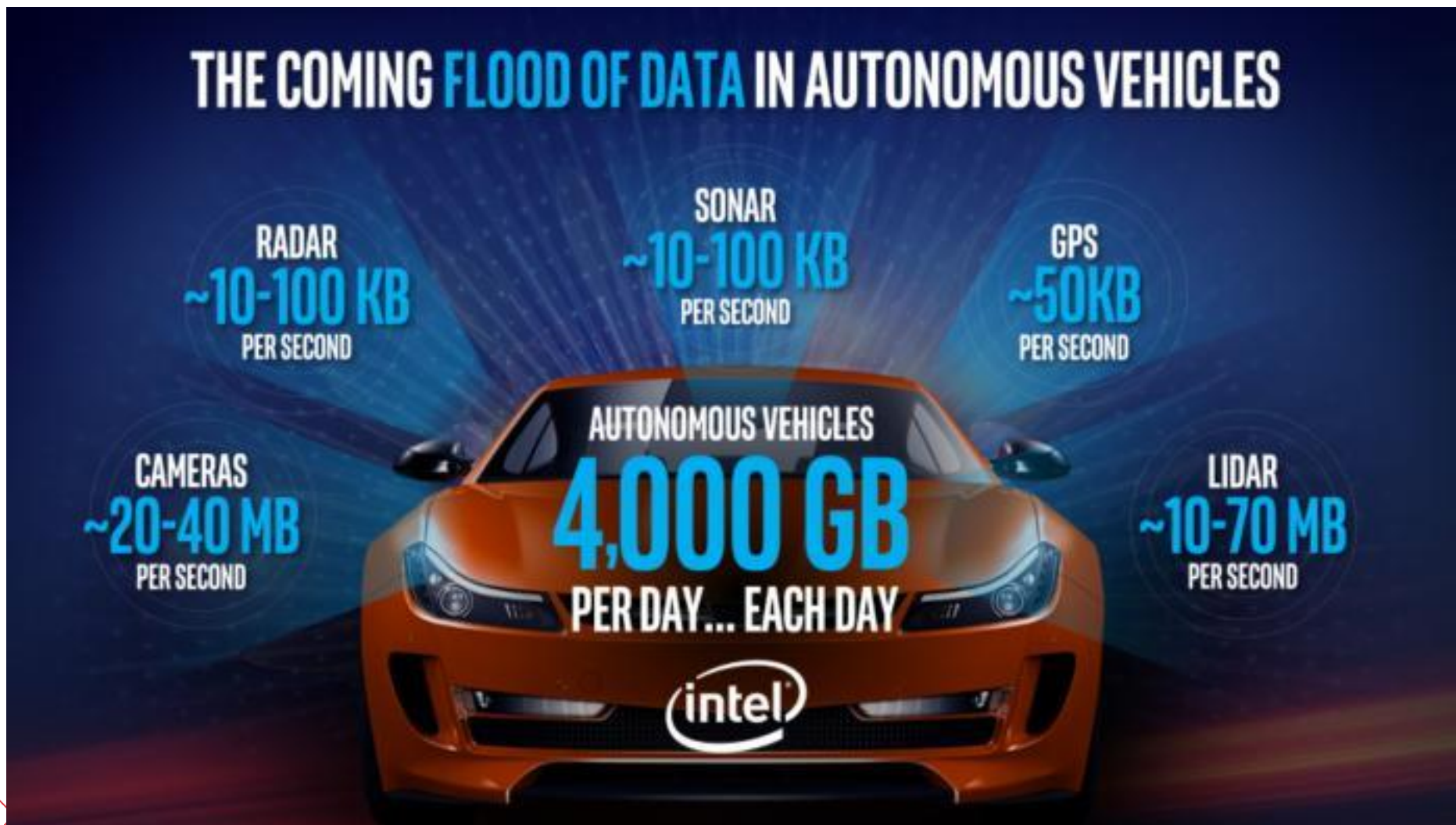
NAND

Cost Effective in Higher Density
SLC Quality can be Competed

Consider a Tough Application Scenario - Automotive

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- ◇ 為什麼對flash 可靠度要求這麼高的汽車應用, 會選擇用SPI NAND來取代SPI NOR ?



 01

從**成本**考慮上，
串列式NAND 相比於串列式NOR，有何優勢？



英国诗人 [Geoffrey Chaucer](#)

“All good things must come to an end”

“所有美好的事物，終會有結束的一天”

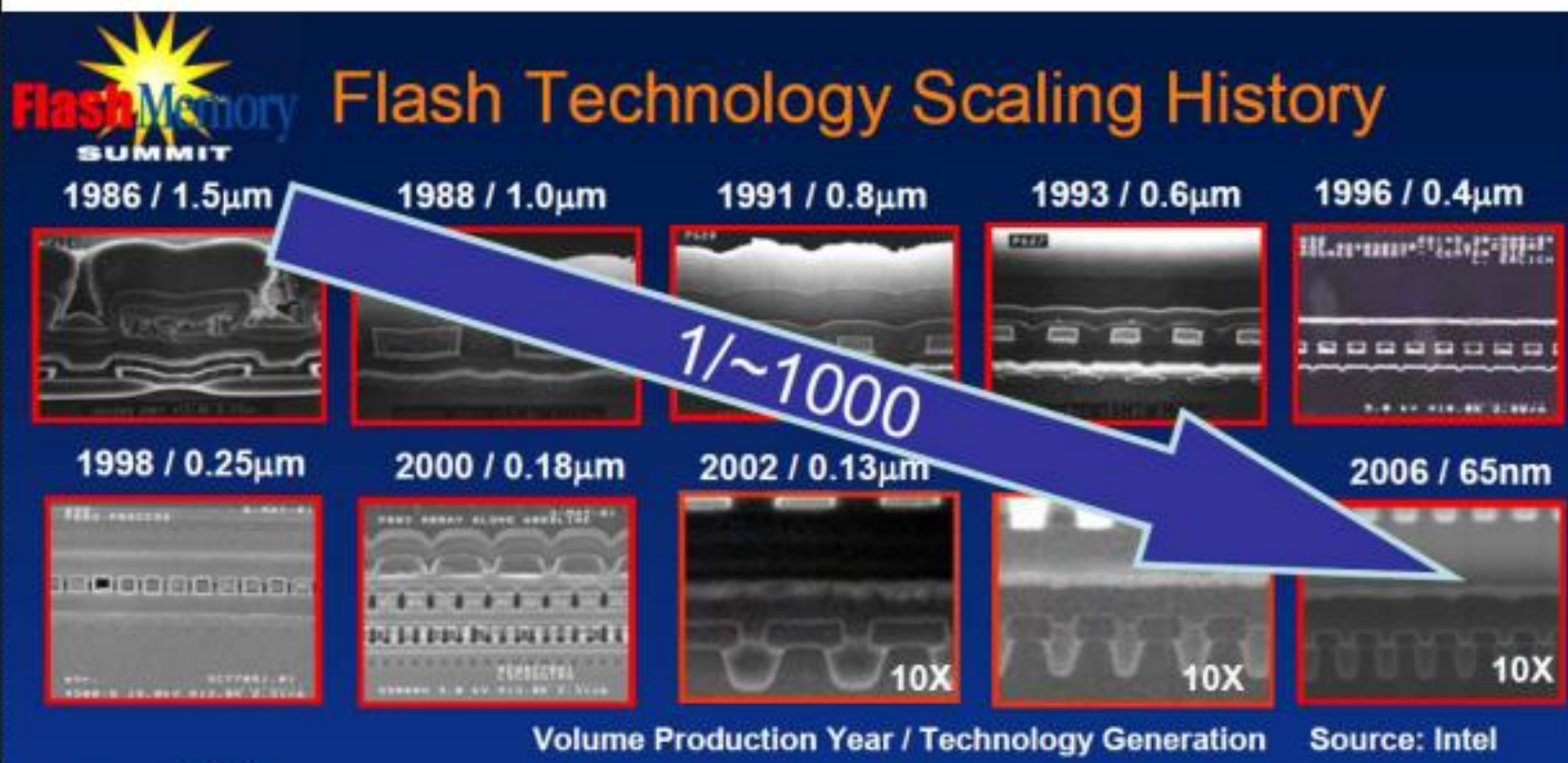
“煙花易冷 人事易分”

NOR scaling slows down @65nm & runs into dead end @45nm.

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This created compelling reason for System Architects to consider SLC NAND at 512Mb~2Gb density . . Further SLC NAND cell size $4F^2$, whereas NOR cell size $10F^2$ (cost difference can be 1:2 at 1Gb density)

Intel had published 45nm NOR Flash paper in IEEE 2008, and NOR Flash is still stalled at 45nm – 10 years later!
"A 45nm NOR Flash Technology with Self-Aligned Contacts and 0.024 μ m² Cell Size for Multi-Level Applications", Fastow, Intel, IEEE 2008⁽¹⁾



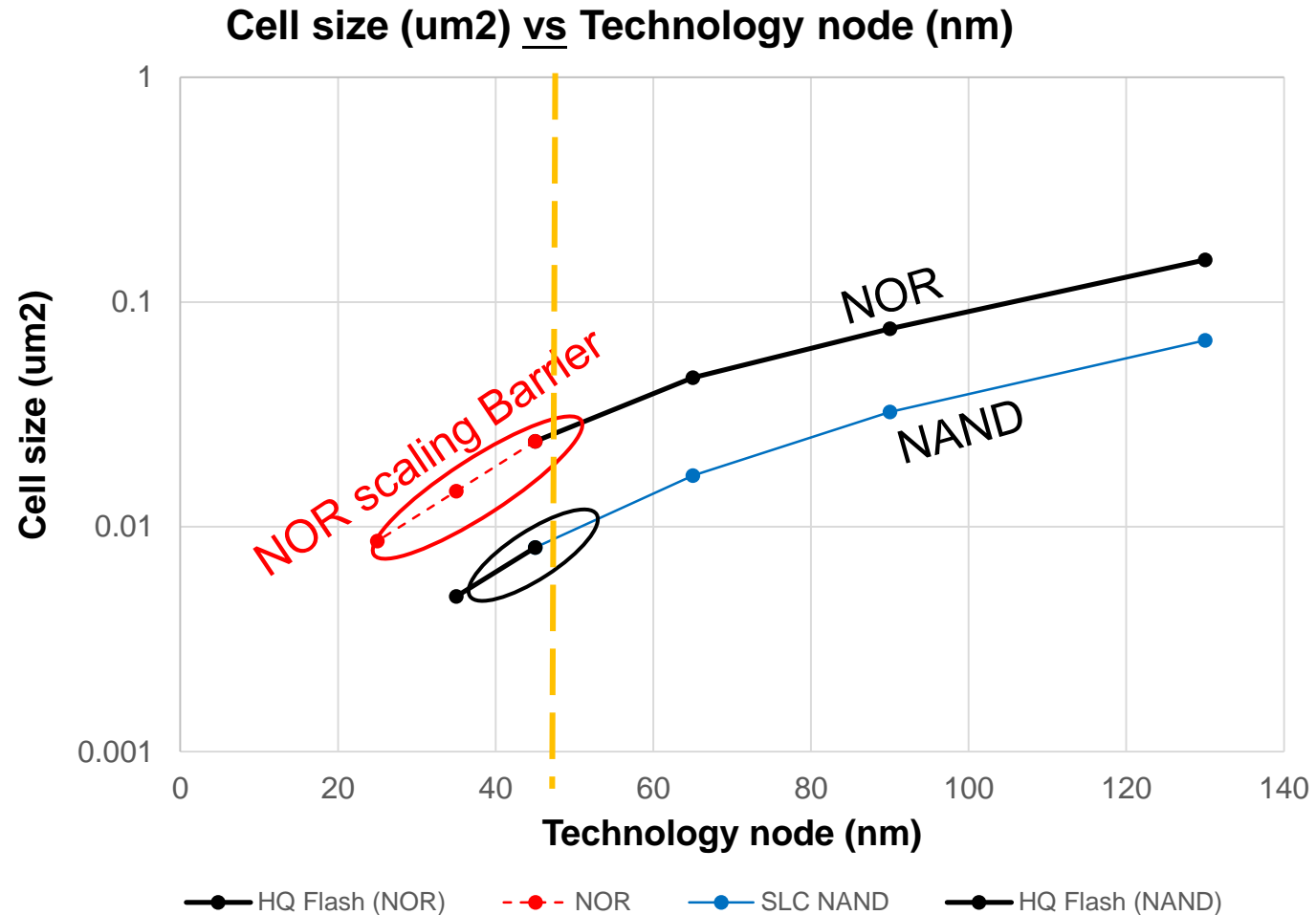
Intel was pioneer in developing multiple gen. of NOR Flash products 1986~2008



Reference for Flash Memory Summit figure: "An Introduction to Emerging Memory Technologies, Greg Komoto", Intel Corporation, Flash Memory Summit , 2007

從成本考慮上，串列式NAND 相比於 NOR，有何優勢？

1Gb Serial NAND is $\sim 1/2$ cost of 1Gb NOR (NAND cell $4F^2$ vs NOR cell $\sim 10F^2$)



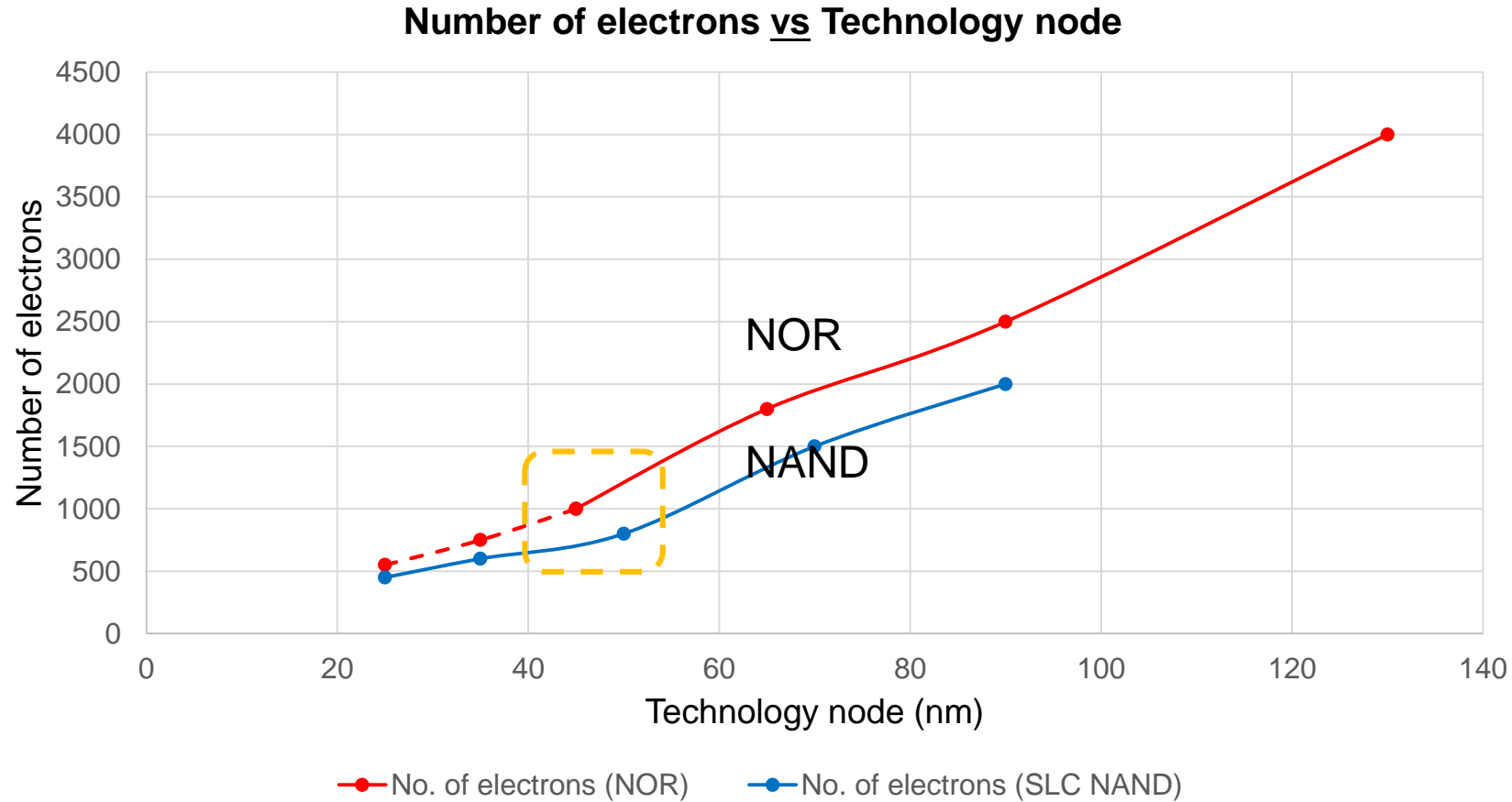
4Xnm NAND extends scaling 2 gen past 45nm NOR:
4Xnm NAND cell size same as extrapolated 25nm NOR

A series of overlapping, hollow red diamond shapes are arranged in a pattern on the left side of the slide, partially overlapping the main text area.

02

從**質量**角度上，
串列式NAND 與串列式NOR 的比較？


4X-nm NAND & 45nm NOR Quality similar, as both have comparable electrons



No. of electrons (NAND) computed for Vt shift of 4V

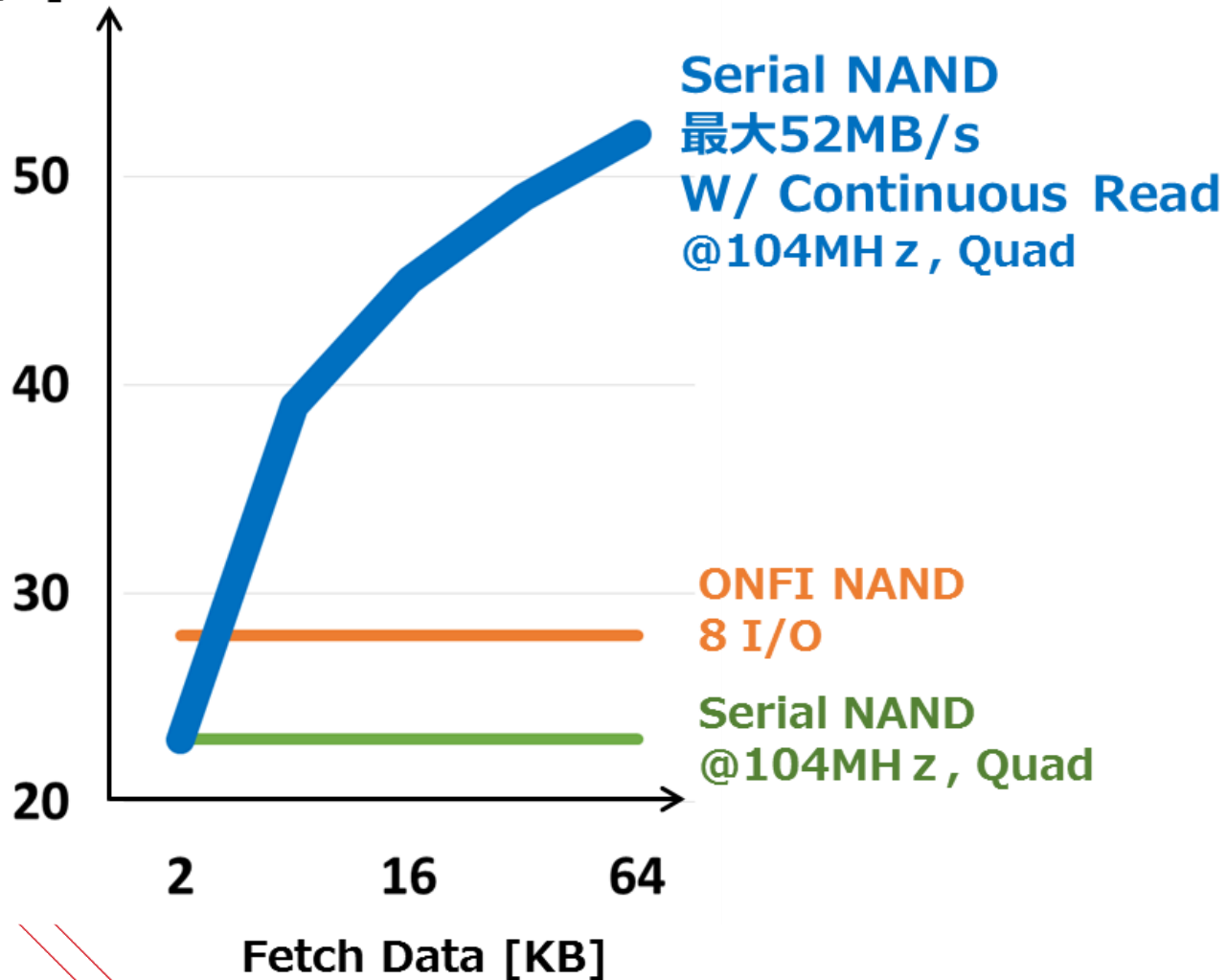
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03

The background of the slide is a composite image. The top right portion shows a close-up of a green printed circuit board (PCB) with several brown square integrated circuits (chips) and various electronic components. The bottom right portion shows a 3D architectural model of a city with numerous yellow and white buildings of varying heights, set against a light blue sky.

從**讀取**速度上，串列式NAND 與
串列式NOR 的比較？

Data Thru-put Rate
[MB/s]



Winbond 獨有
Continuous Read

最高 52MB/s
資料傳輸速度

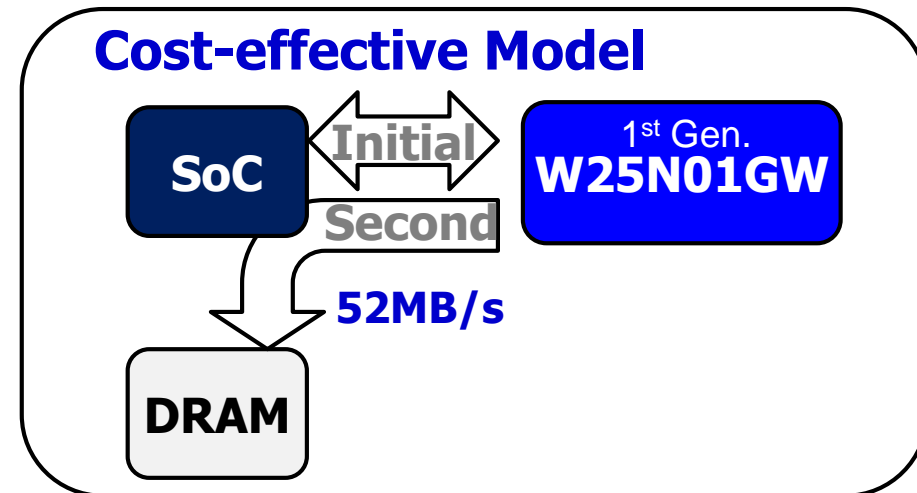
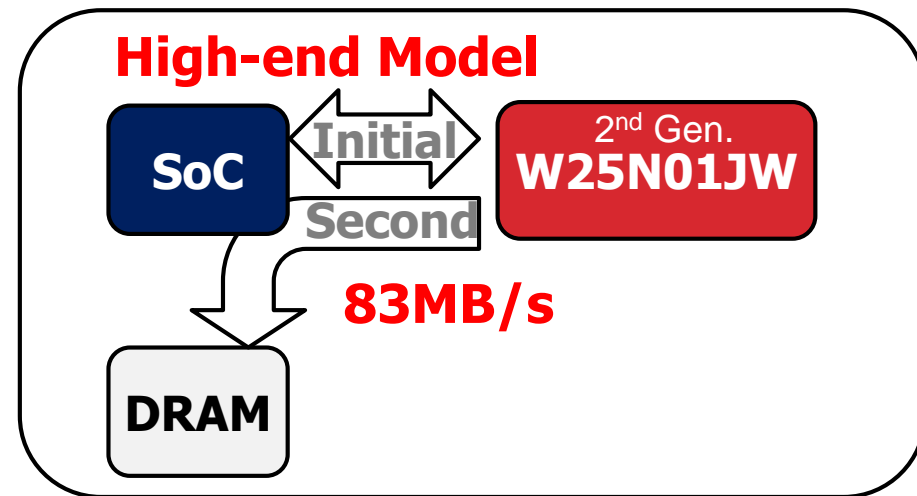
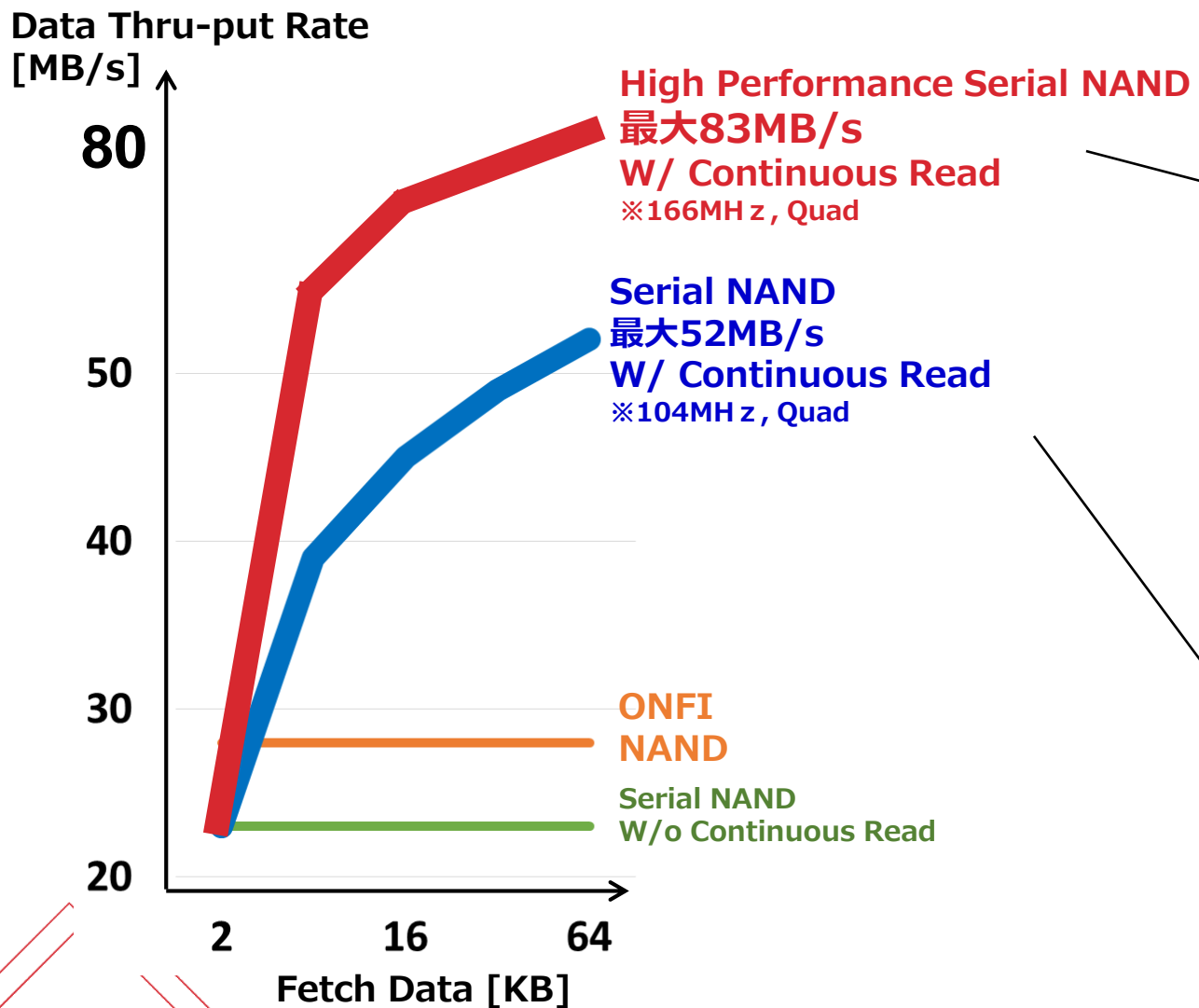
First Born in the World

WINBOND 2nd gen. Serial NAND

High
Performance

- STR=166Mhz
- DTR= 83Mhz
- Read 83MB/s

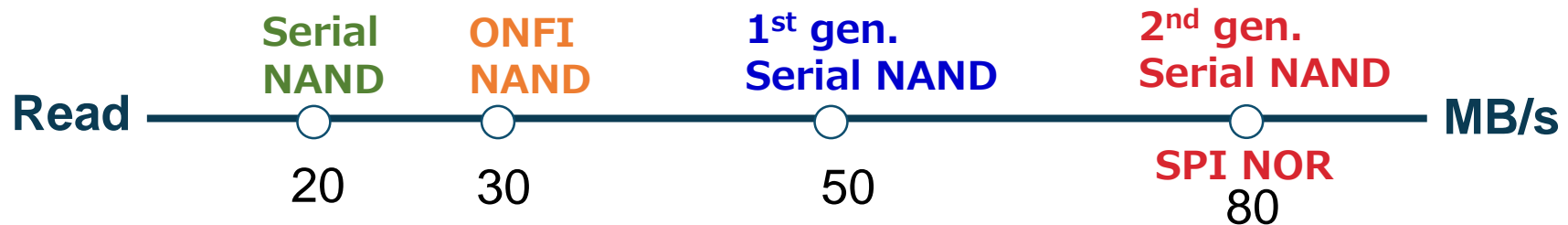
Continuous Read with 2nd gen. Serial NAND – High Performance Serial NAND



從讀取速度上，串列式NAND 與串列式NOR 的比較？

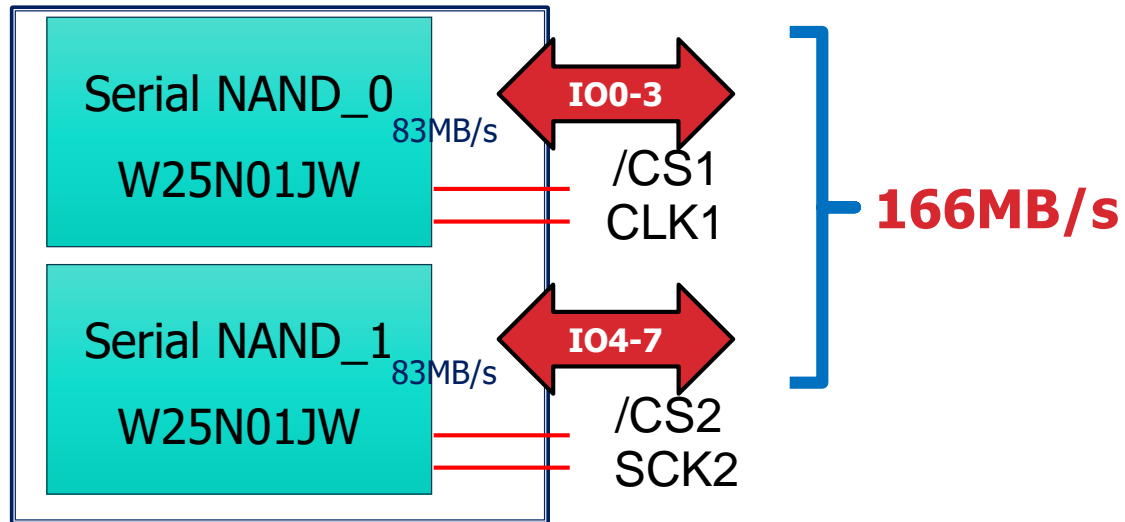
◇ Winbond 2nd gen Serial NAND compete with NOR in Read!

		Quad Interface	
		SPI NOR: W25H256JV	2nd gen. Serial NAND: W25N01JW
Sample status		NOW	Sampling
Process		58nm	46nm
Density		256Mb	1Gb
VCC (Supply Voltage)		3V	1.8V
Read	Spec	STR 133MHz DTR 80MHz	STR 166MHz DTR 83MHz
	MB/s	80 MB/s	83 MB/s
On-chip ECC		Yes	Yes
Signal #s (Except Vcc/GND)		7 signals (includes /RST)	7 signals (includes /RST)

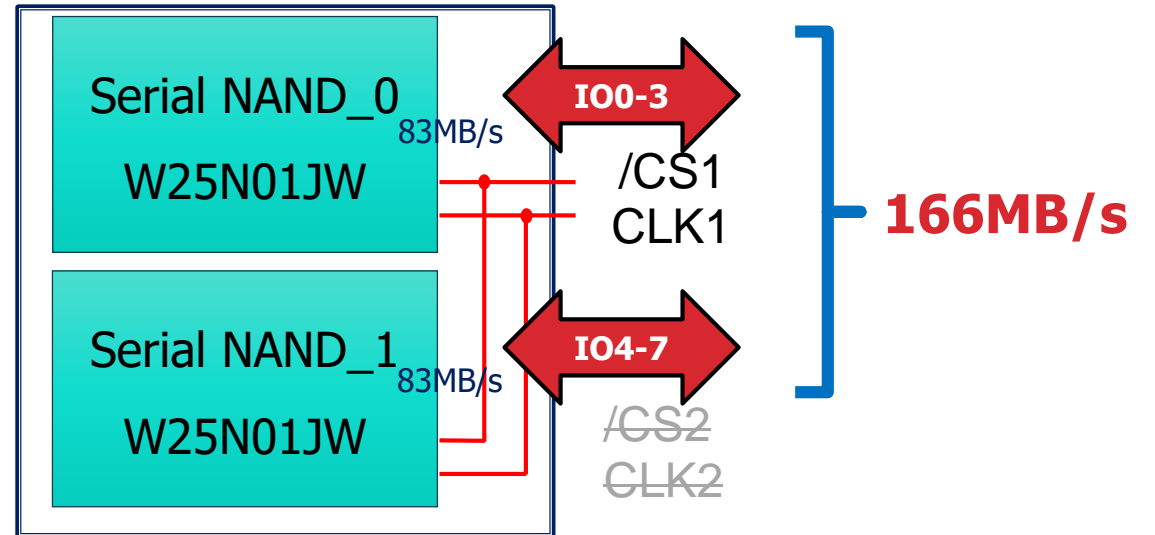


Two chips in One Package

1st Step : Parallel control



2nd Step : Single control



8 I/O **166MB/S**

- Single Package
- Dual Quad
- W72N Series

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04

The background of the slide is a composite image. The top right portion shows a close-up of a green printed circuit board (PCB) with several brown square integrated circuits (chips) and various electronic components. The bottom right portion shows a 3D architectural model of a city with numerous skyscrapers and buildings. A diagonal white line separates the two images.

從寫入速度上，
串列式NAND 與串列式NOR 的比較？

從寫入速度上，串列式NAND 與串列式NOR 的比較？



Serial NAND

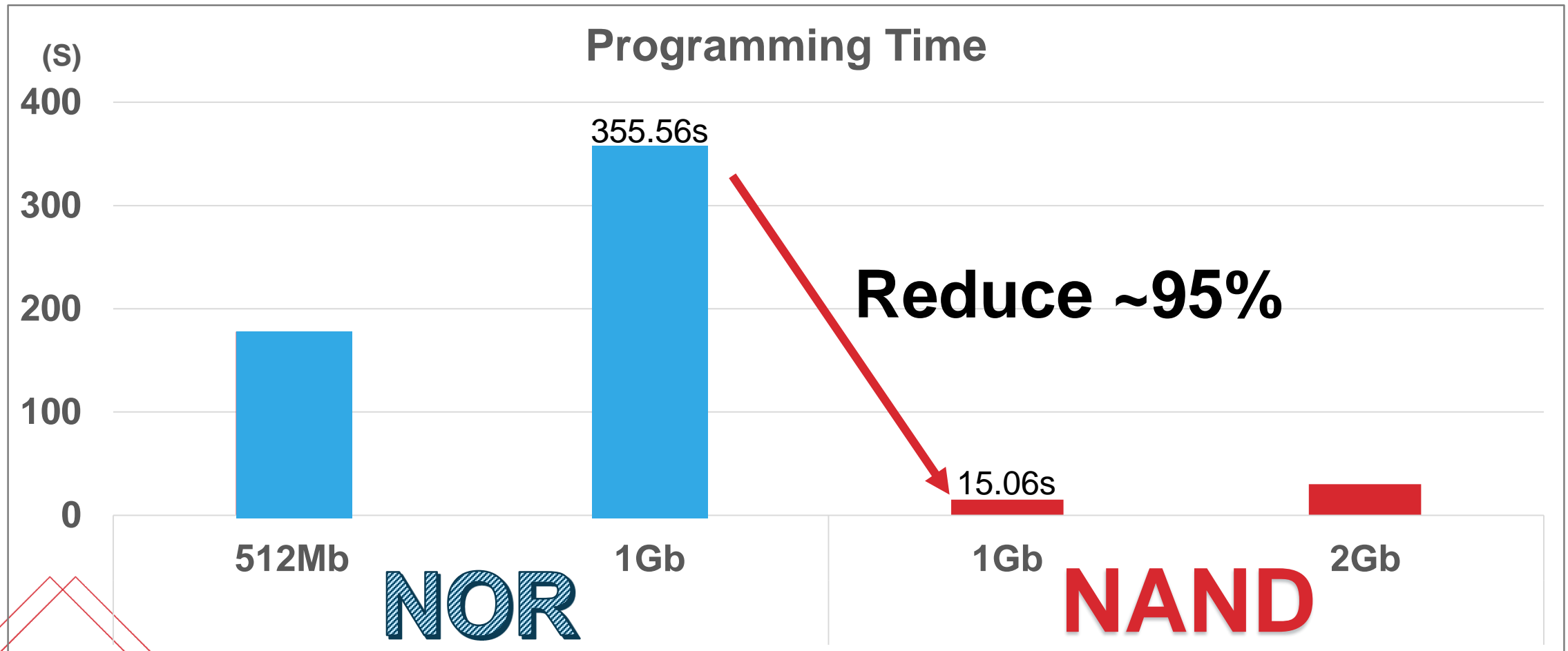
**寫入速度 >10 倍快
擦除 >100 倍快**

than NOR

		Quad Interface	
		SPI NOR: W25H256JV	2nd gen. Serial NAND: W25N01JW
*1 : Quad mode *2 : Quad mode & Cont. read *3 : On chip ECC = enable			
Sample status		NOW	Sampling
Process		58nm	46nm
Density		256Mb	1Gb
VCC (Supply Voltage)		3V	1.8V
Program	Spec	700us	250us
	Size	256 Byte	2048 Byte (+ 64 spare Byte)
	MB/s	0.36 MB/s	8.5 MB/s
Erase	Spec	30ms / 150ms	2ms
	Size	4KB / 64KB	128KB
On-chip ECC		Yes	Yes
Signal #s (Except Vcc/GND)		7 signals (includes /RST)	7 signals (includes /RST)

Saving Programming Time

- ◇ 快速燒錄, 降低生產成本
- ◇ 快速線上更新, Fast OTA



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05

**串列式NAND 需要額外控制器做
壞塊管理或 ECC 嗎？**

◇ Serial NAND with on-chip ECC and BBM with LUT

Features in “Managed NAND”	eMMC	Winbond Industrial Grade Serial NAND	Winbond Automotive Grade Serial NAND
ECC (錯誤糾正碼)	Fully built-in	Fully built-in	Fully built-in
Bad Block Management (壞塊管理)	Fully built-in	<ul style="list-style-type: none"> Built in hardware LUT 	<ul style="list-style-type: none"> Shipping with zero initial bad block. (出廠零壞塊) Built in hardware LUT
Wear leveling (耗損均衡)	Fully built-in	<ul style="list-style-type: none"> Not necessary for few thousand P/E cycles per block Winbond 46nm Industrial grade NAND Qualified to JEDEC Qual for 100K cycle 	<ul style="list-style-type: none"> Not necessary for few thousand P/E cycles per block Winbond 46nm Automotive grade SLC NAND Qualified to AEC-Q100 Qual for 10K cycle

Automotive:

- Winbond takes lead in Industry to offer Automotive Grade NAND part with “0” initial bad block.
- Winbond offers “Block swap” command (A1h) as well as ability to store Address mapping LUT for BBM in the Flash chip.

Decorative red-outlined diamond shapes are arranged in a pattern on the left side of the slide, partially overlapping the text area.

06

最後：華邦 串列式NAND 產品特色
總結串列式NAND帶來的優勢

◇ 華邦 串列式NAND W25N系列 產品特色

● Seamless transition to *Serial NAND* with **standard SPI interface** and package

- **46nm** SLC NAND technology in Winbond's 12" wafer Fab
- **512Mb, 1Gb and 2Gb** density available now
- **3V / 1.8V** power supply
- *Continuous Read* **52MB/s Data Throughput** ideal for Code-Shadowing
- **Low pin-count** packages (WSON-8, TFBGA-24) with MCP options
- On Chip **1-Bit ECC** and On Chip **Look-Up-Table** for Bad Block Management
- **Industrial** grade & **Automotive** grade
- *Flexible device configurations* by customers' need (Buffer/Continuous Read, Array/Device Lock-Down/OTP/write protection)

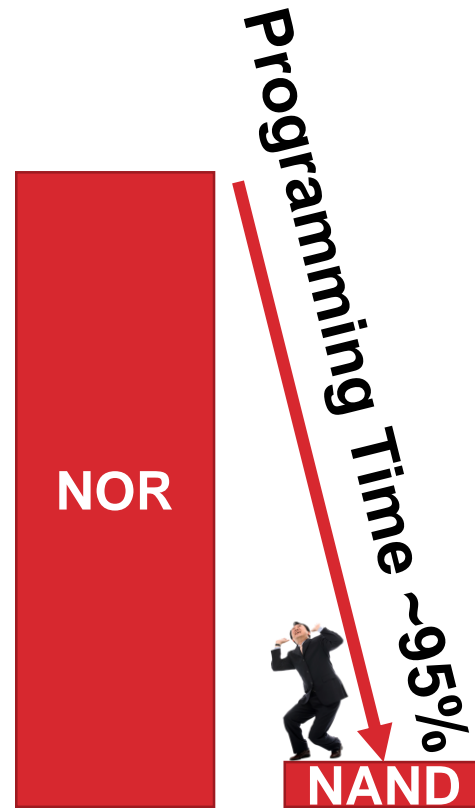
SPI Interface, 8-pin small package

Built-in features offloads external controller – ECC, Bad Block Management

Continuous Read – Improves system efficiency



總結 串列式NAND的優勢



Same Quality Level



A hand in a suit jacket points towards a futuristic digital interface. The interface features glowing blue and red lines, a cityscape at night, and various icons like a key, a gear, and a speech bubble. In the center, there is a block of Python code. The text "Autonomous Driving" is visible in the upper left of the interface.

Thank You

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